



# Modeling of an Edge-Emitting strained-Ge laser

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innovations  
for high  
performance  

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microelectronics

January 27<sup>th</sup> 2016

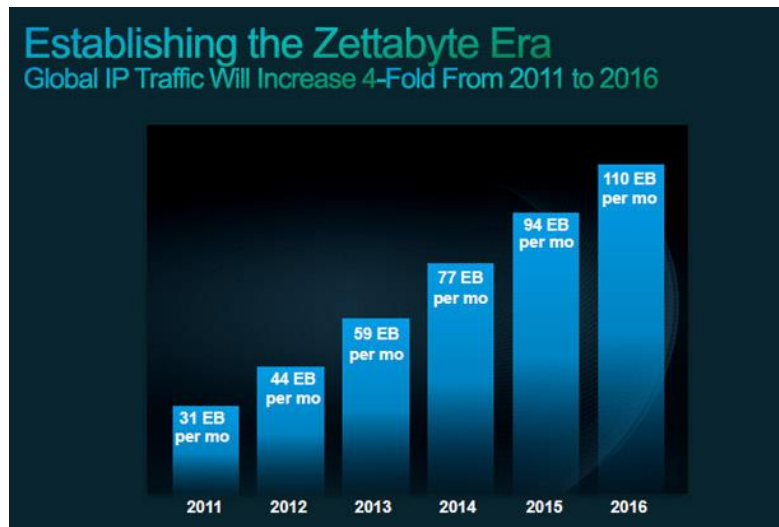
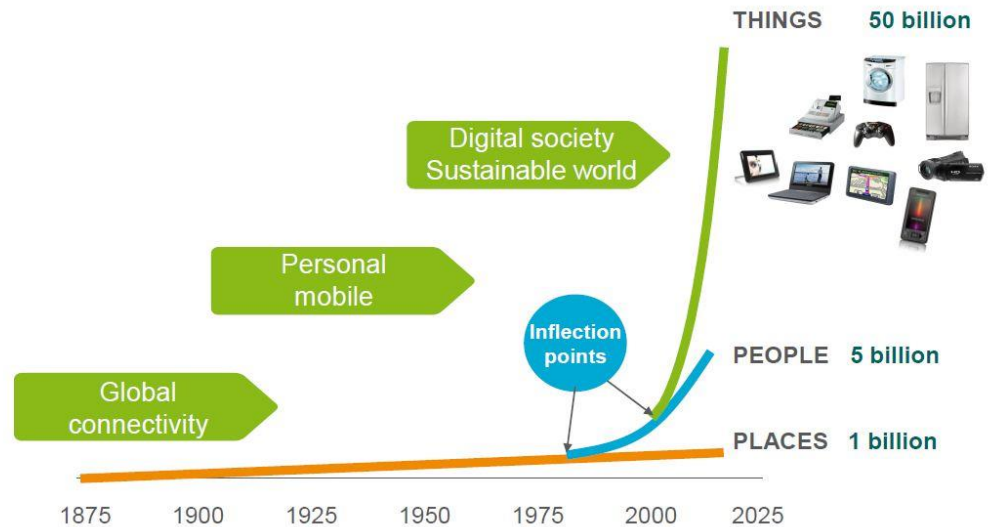
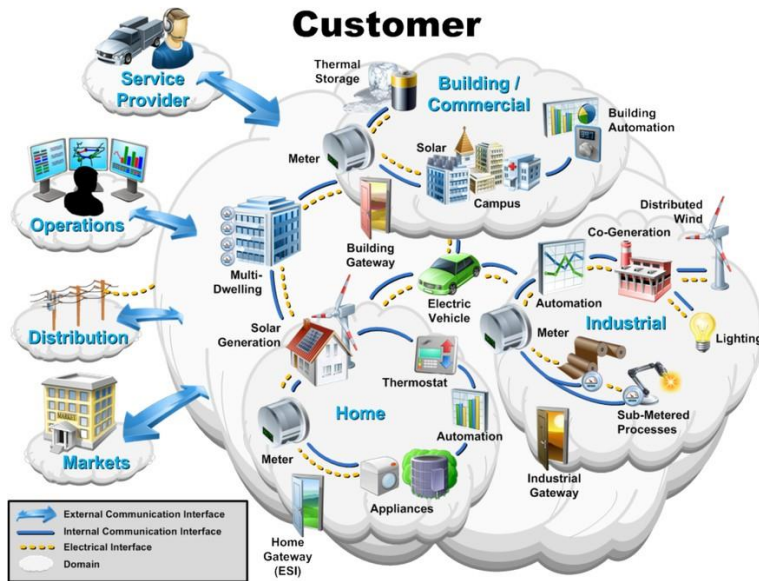
MMSDays 2016



Member of



# Motivation: the connected world



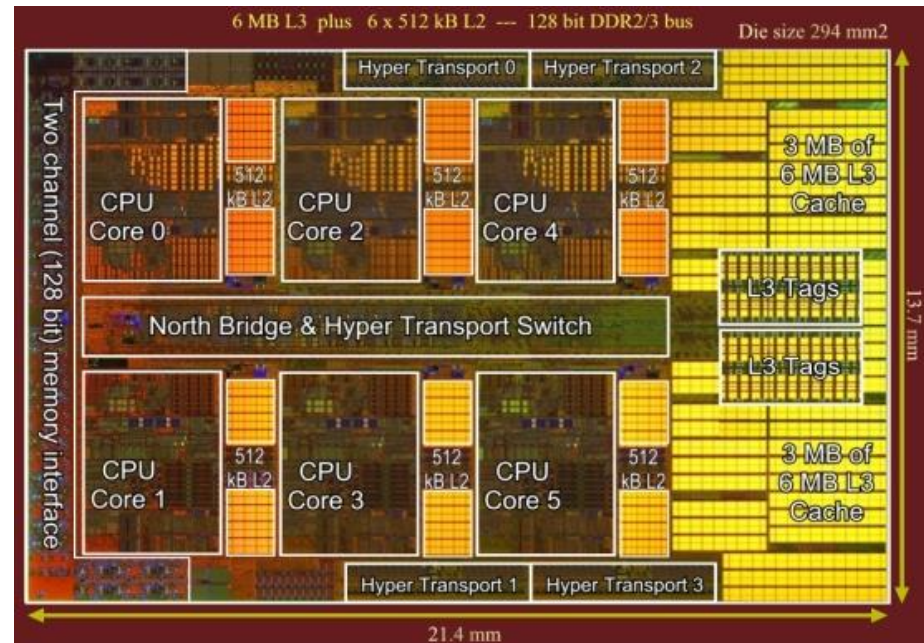
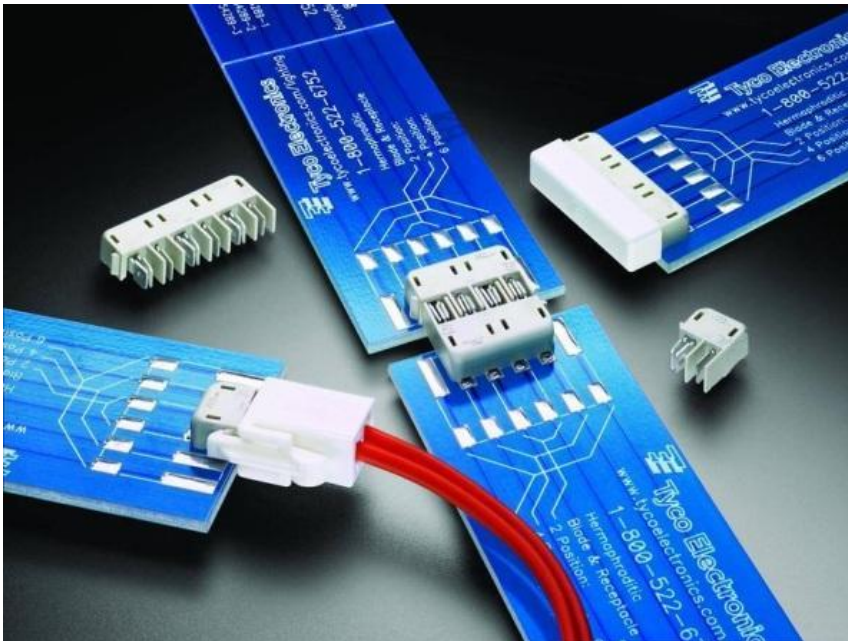


# Motivation: bandwidth, bandwidth, and bandwidth

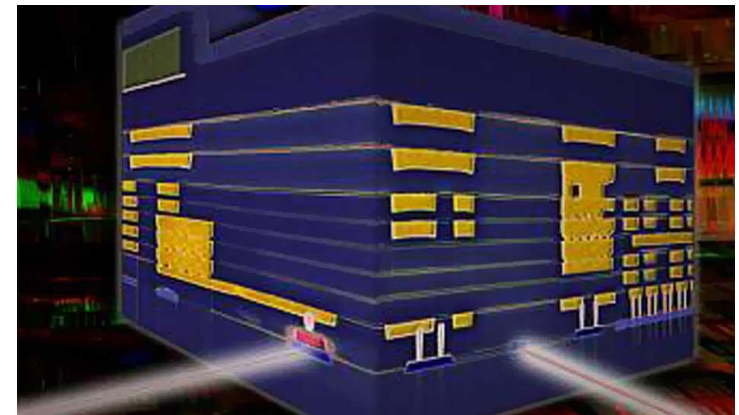
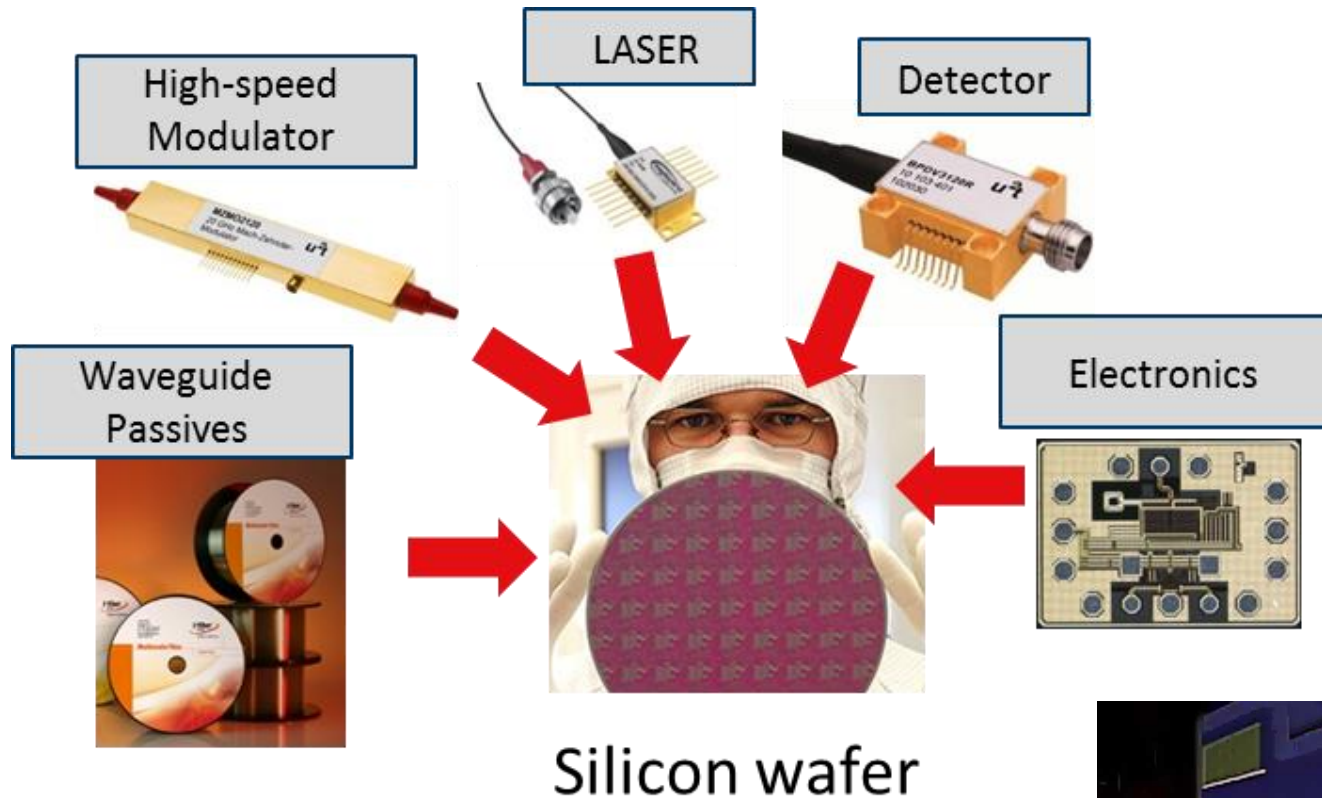


More bandwidth and lower power consumption needed at all scales:

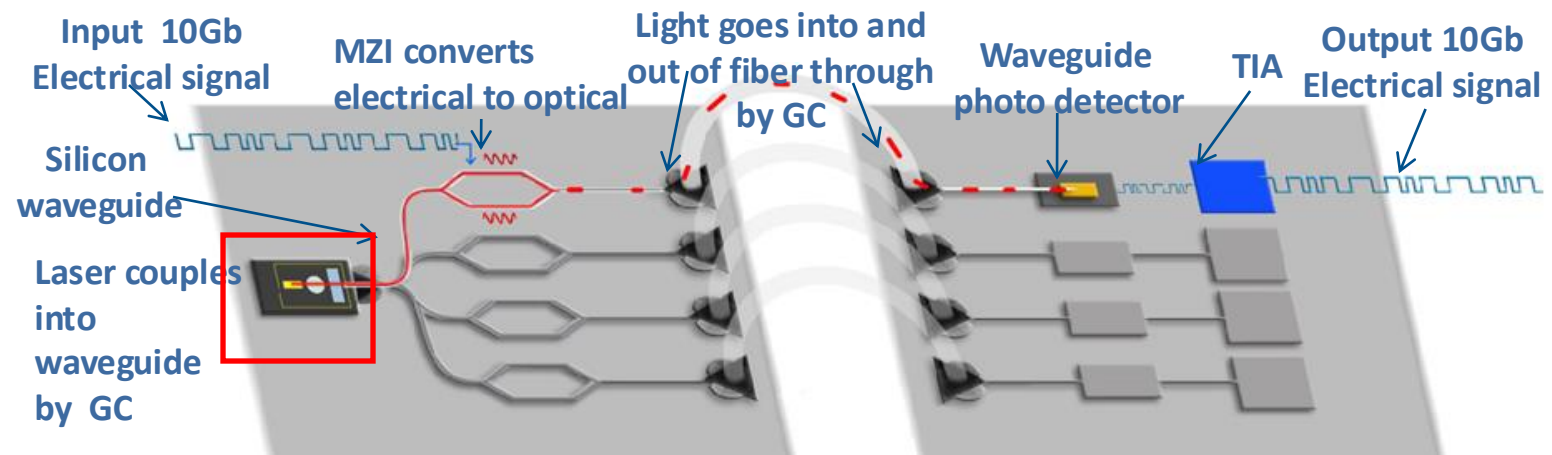
- Rack-to-Rack
- Board-to-Board
- Chip-to-Chip



# Bringing light to the chip: a More-than-Moore solution



# Light on chip: Laser is the Holy Grail

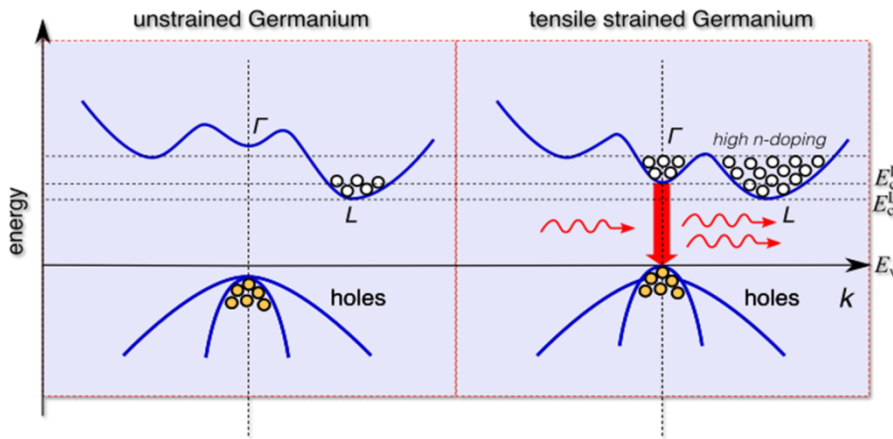


**Integrated laser is the only missing piece: a Ge Laser?**

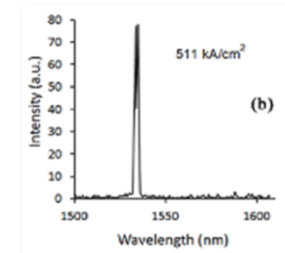
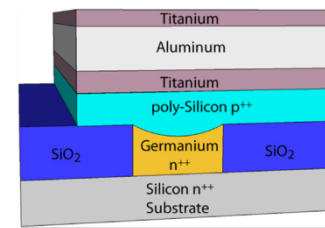


# Ge-Laser

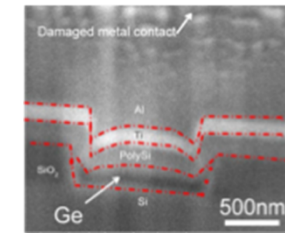
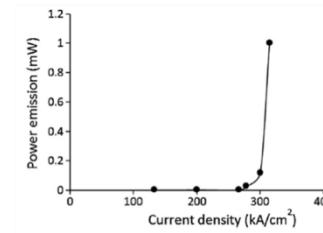
**TOWARDS A LASER MONOLITHICALLY INTEGRATED IN THE SILICON PHOTONICS:**  
how to turn a group IV semiconductor in a direct band gap material



**OK: INTEGRABLE, EMISSION DEMONSTRATED**



**KO: LARGE  $I_{th}$ , LIMITED DEVICE LIFETIME**



- **TENSILE STRAIN**
- **ULTRA-HIGH n DOPING (difficult in Ge)**
- **ALLOYING WITH Sn**

## RT Electrically pumped Ge laser

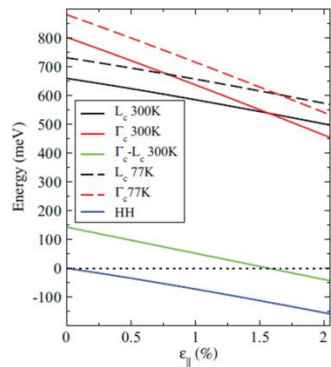
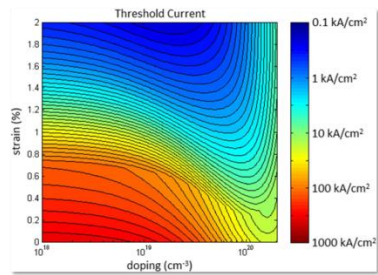
Camacho-Aguilera (MIT), 2012 :  $\epsilon_{bi}=0.2\%$   $I_{th}\sim 300\text{kA/cm}^2$   $W_{out}<1\text{mW}$   $\lambda\sim 1.6\text{-}1.7\ \mu\text{m}$   $n_{dop}\sim 4\times 10^{19}\text{cm}^{-3}$

Koerner (IHT), 2015:  $\epsilon_{bi}<0.2\%$   $I_{th}\sim 500\text{kA/cm}^2$   $W_{out}<1\text{mW}$   $\lambda\sim 1.66\text{-}1.7\ \mu\text{m}$   $n_{dop}\sim 3\times 10^{19}\text{cm}^{-3}$

## T=80K Optically pumped GeSn laser

Wirths (FZ-Juelich), 2015 :  $x\text{Sn}=0.13$   $\epsilon_{bi}=-0.7\%$   $P_{th}\sim 325\text{kW/cm}^2$   $W_{out}=NA$  (gain  $\sim 100\text{cm}^{-1}$ )  $\lambda\sim 2.25\ \mu\text{m}$

B. Dutt et al., *IEEE Photon. J.* 4, (2012)

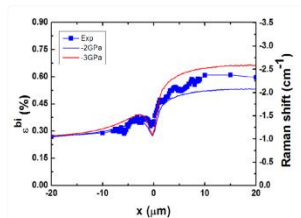
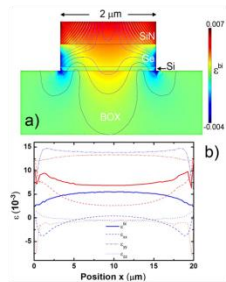
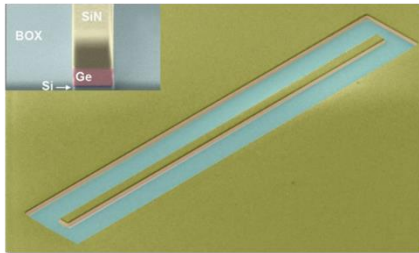


M. Virgilio et al., *Phys.Rev. B* 87, 235313 (2013)

# Modeling strategy

## FROM MATERIAL PROPERTIES TO FULL 2D OPTOELECTRONIC SIMULATIONS: UPSCALING

### MATERIAL FABRICATION AND FEM OF THE ELASTIC PROPERTIES. EXPERIMENTAL VERIFICATION

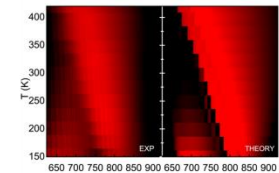
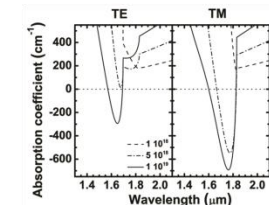


G. Capellini et al., *Optics Express* **22**, 399 (2014)  
G. Capellini et al., *J. Appl. Phys.* **113**, 013513 (2013)

STRAIN FIELD

### QUANTUM MODELING OF THE ELECTRONIC PROPERTIES (TB). EXPERIMENTAL VERIFICATION

- Multi-valley effective mass and deformation potential theory
- Direct and indirect recombination from Fermi golden rule
- Spatially resolved excess carrier distribution (Surface, Auger, and SRH recombination, doping and carrier diffusion)
- Strain effect on the dipole matrix elements
- Spatially resolved self-absorption effects to relate  $R_{int}(\omega)$  to external PL



OPTICAL PROPERTIES

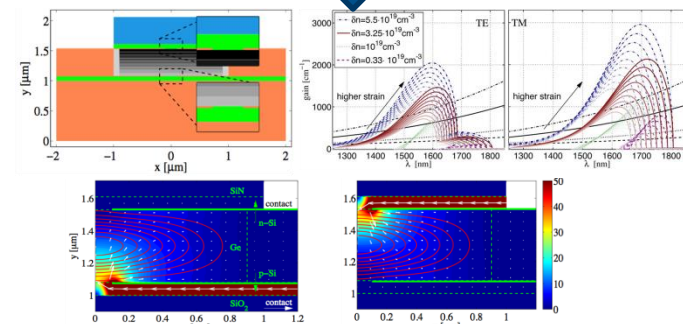
### FULL 2D OPTOELECTRONIC SIMULATIONS

#### INPUT IN WIAS TeSCA:

- Device 2D geometry including doping. FB cavity with or w/o aperture
- Spatially-resolved spectral gain as a function of carrier density, strain, and polarization

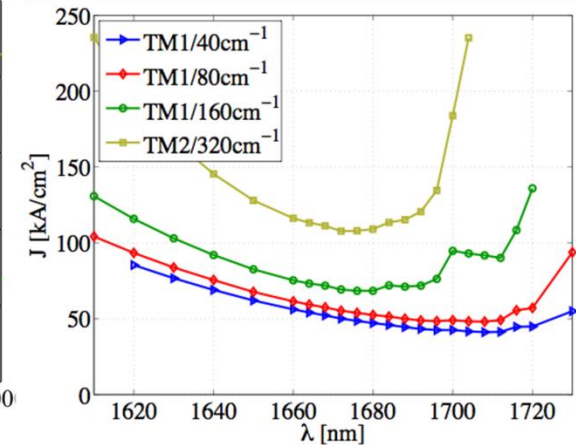
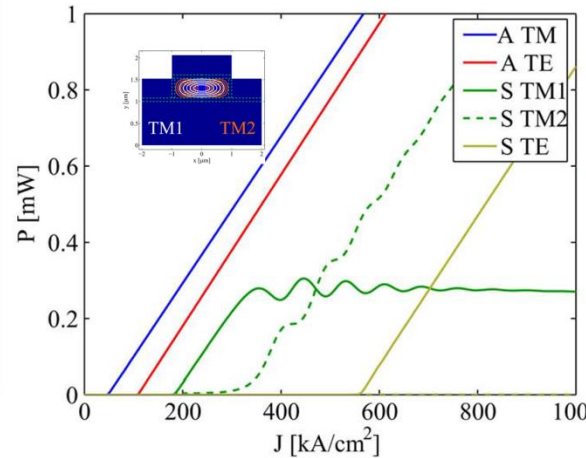
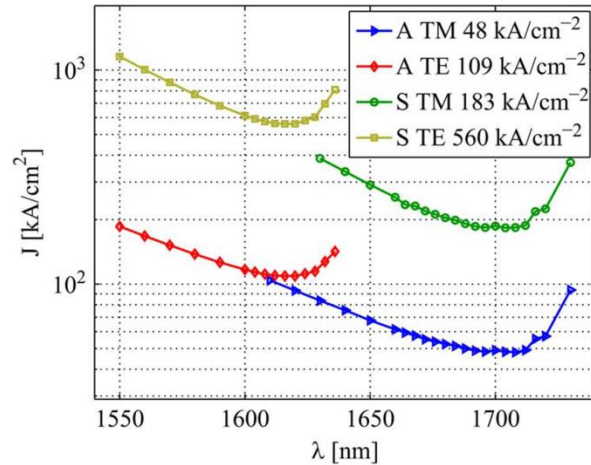
#### Calculation includes

- the van Roosbroeck system
- the Helmholtz equations for the transverse optical field
- the balance equations for the corresponding photon numbers

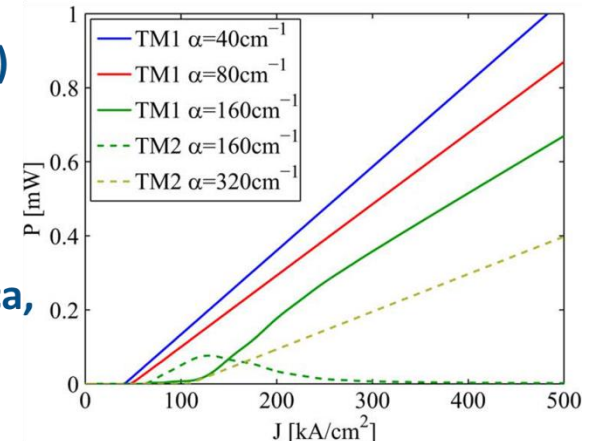




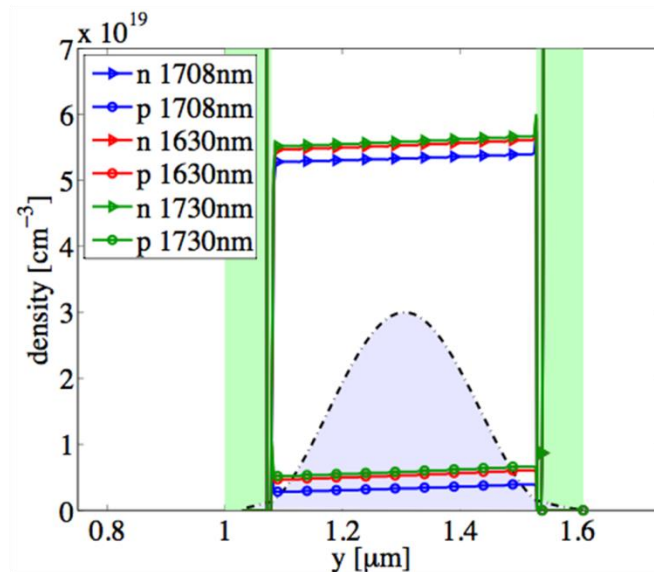
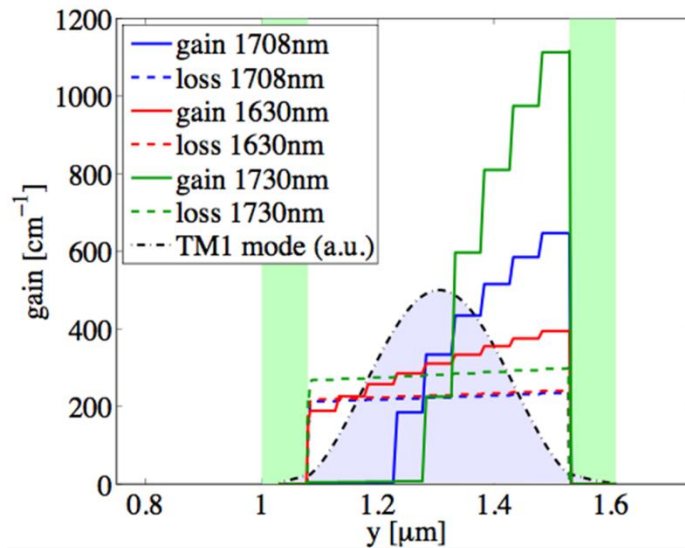
# Results and Outlook



- **TM PREFERRED OVER TE (higher gain due to LH-HH splitting)**
- **APERTURE INJECTION REDUCES THRESHOLD BY 4×**
- **EMISSION POWER IN THE mW RANGE AT 30 mA**
- **BLUE SHIFTED EMISSION FOR HIGHER LOSSES (wg, mirror, fca, etc. Agrees with MIT)**
- **SWITCHING TO TM2 AT HIGHER LOSSES**



# Results and Outlook



**INHOMOGENEOUS  
STRAIN DISTRIBUTION**



**SPATIALLY-DEPENDENT  
GAIN**



**MATERIAL GAIN**

$\neq$

**MODAL GAIN**



**OVERLAP ENGINEERING**



# Thank you for your attention!

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